CN11-2018
CMV20000 Test diode pads unbonding

Dear Customer,

In order to ensure continuous improvement and increase reliability of our products, ams Sensors Belgium has decided to remove test diode bonding wires on CMV20000.

Impact on product performance
There will be no impact on product performance. The pins that will no longer be connected, had no use for the operation of the sensor.

Impact on supply chain
The implementation into our products will not create a delay in deliveries.

Impact on reliability/qualification status
The change is part of our continuous improvement and will ensure better protection against ESD events in rare cases.
The following product versions will be affected:

<table>
<thead>
<tr>
<th>Part</th>
<th>Description</th>
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<tbody>
<tr>
<td>302030004</td>
<td>CMV20000-1E5C1PA QA</td>
</tr>
<tr>
<td>302030003</td>
<td>CMV20000-1E5C1PN QA</td>
</tr>
<tr>
<td>302040004</td>
<td>CMV20000-1E5M1PA QA</td>
</tr>
<tr>
<td>302040005</td>
<td>CMV20000-1E5M1PN QA</td>
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</tbody>
</table>

Timing of change
Ams will introduce this change in the assembly process, as soon as this CN is communicated.

Verification strategy
Verification of the operation of the sensors is performed through our production device tests.

Traceability
Traceability from assembly with a starting ARF number will be logged.

Verification of implementation
Verification of the removed wires will be done visually in the first incoming batches.

If you do have further questions please do not hesitate to contact us.

Best regards,

Michael Pfleger
ams AG
Director Operations ISS